A. Interconnect & Package 분과

Room A
1F / 104호

2015년 2월 11일(수) 09:00-10:30
[WA1-A] TSV & Microbump
좌장: 이후정 (성균관대학교), 조철호 (SK Hynix Inc.)

WA1-A-1	**09:00-09:15**	**Tackling High Volume Production of 3DI/TSV Packages** Hugo Pristauz Besi Austria GmbH
WA1-A-2	**09:15-09:30**	**Characteristics of Through-Si-Via(TSV) Filling by Electrodeposition with Pulse Wave Form Current** Sanghyun Jin and Bongyoung Yoo Department of Materials Engineering, Hanyang University
WA1-A-3	**09:30-09:45**	**Temporary Bonding and Debonding Technology to Enable Cost-Effective Fabrication of Through-Glass-Via Interposers** Alvin Lee[1], Jay Su[1], Kim Arnold[1], Dongshun Bai[1], Bor Kai Wang[2], Leon Tsai[2], Aric Shorey[2], Wen-Wei Shen[3], Chun-Hsien Chien[3], Hsiang-Hung Chang[3], and Jen-Chun Wang[3] [1]Brewer Science, Inc., [2]Corning Advanced Technology Center/Corning Incorporated, [3]Electronics and Optoelectronics Research Laboratories (EOL), Industrial Technology Research Institute (ITRI)
WA1-A-4	**09:45-10:00**	**Effect of the microstructure of electroplated Ni UBM on the Growth of Ni-Cu-Sn Intermetallic Compound in Flip-Chip Packaging** Mi-Seok Park, Do-Hwan Nam, and Hyuk Sang Kwon Department of Materials Science and Engineering, KAIST
WA1-A-5	**10:00-10:15**	**Mechanisms of Improving Thermal Cycling Reliability with Pad Finish & Solder Alloying Effect on Solder Grains** Jung-Lae Jo, Soon-Bum Kim, Tae-Eun Kim, Yeo-Hoon Yoon, Ho Jeong Moon, Hyunggil Back, Tae-Je Cho, and Sayoon Kang Reliability & Analysis Part, Fundamental Technology PJT., Package Development Team, Semiconductor R&D Center, SAMSUNG ELECTRONICS CO., LTD.
WA1-A-6	**10:15-10:30**	**Comparison of Creep Models for Solder Alloys** Yongchang Lee Sk Hynix Inc., Package and Test center, Interconnect Product & Technology (IPT) development group